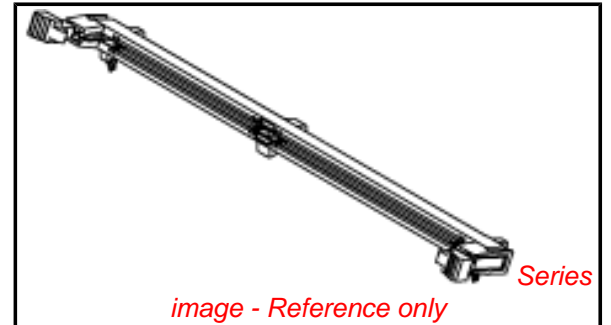


**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0876232111](#)  
**Status:** **Active**  
**Description:** 1.27mm (.050") Pitch DDR DIMM Socket, Low Profile (25°), Single Key, with Beveled Metal Pins and Plastic Pegs, 3.18mm (.125") Tail Length, with 4.83mm (.190") Locating Pegs, 0.76µm (30µ") Gold (Au) Plating, 184 Circuits, Leadfree

**Documents:**

[3D Model](#) [Product Specification PS-87623-002 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)



**General**

Product Family	Memory Module Sockets
Series	<a href="#">87623</a>
Component Type	Memory Module
JEDEC Outline	MO-206
Product Name	DDR DIMM

**Physical**

Circuits (Loaded)	184
Color - Resin	Black, Natural
Durability (mating cycles max)	25
Entry Angle	25° Angle
Keying to Mating Part	Yes
Material - Metal	Brass, Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
PC Tail Length (in)	0.125 In
PC Tail Length (mm)	3.18 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.050 In
Pitch - Mating Interface (mm)	1.27 mm
Plating min: Mating (µin)	30.4
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	101.6
Plating min: Termination (µm)	2.54
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Through Hole

**Electrical**

Current - Maximum per Contact	1A
Voltage - Maximum	50V
Voltage Key	2.5V, Left

**Solder Process Data**

Duration at Max. Process Temperature (seconds)	10
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	260

**Material Info**

**Reference - Drawing Numbers**

**EU RoHS**

**ELV and RoHS  
Compliant**  
**REACH SVHC**  
 Not Reviewed  
**Halogen-Free  
Status**  
 Not Reviewed

**China RoHS**



**Need more information on product  
environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[87623Series](#)

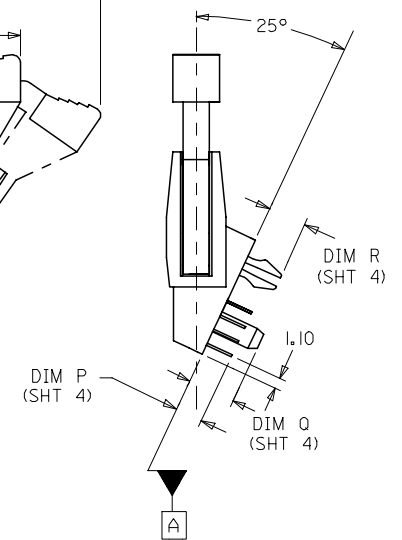
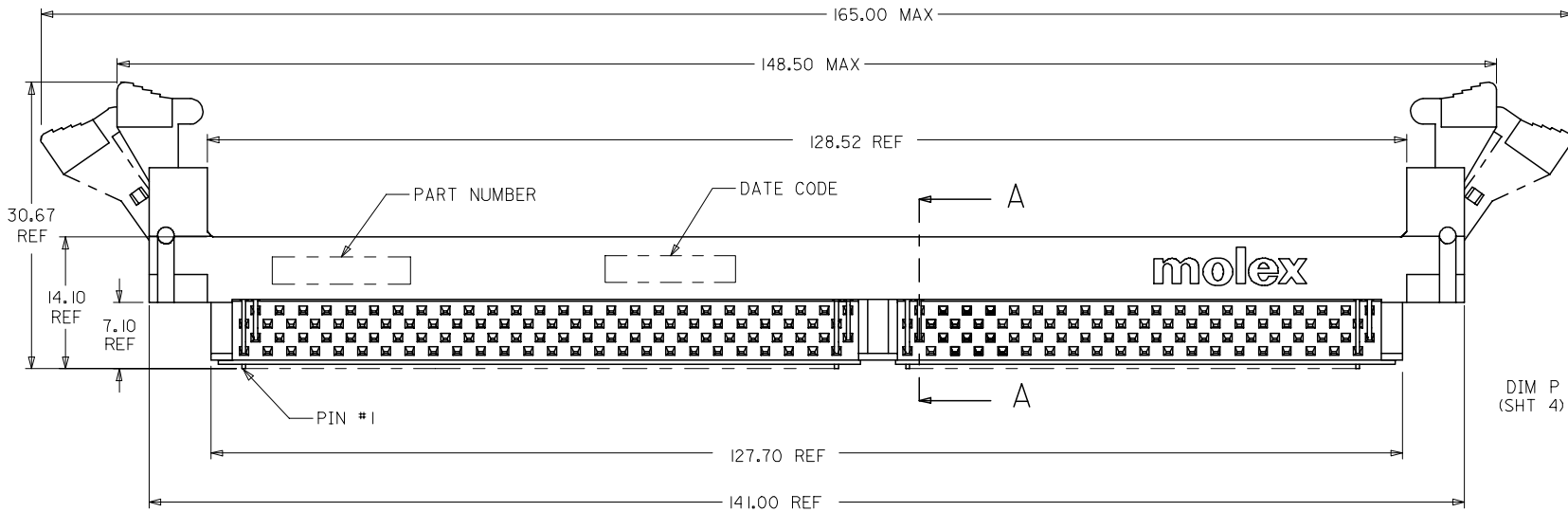
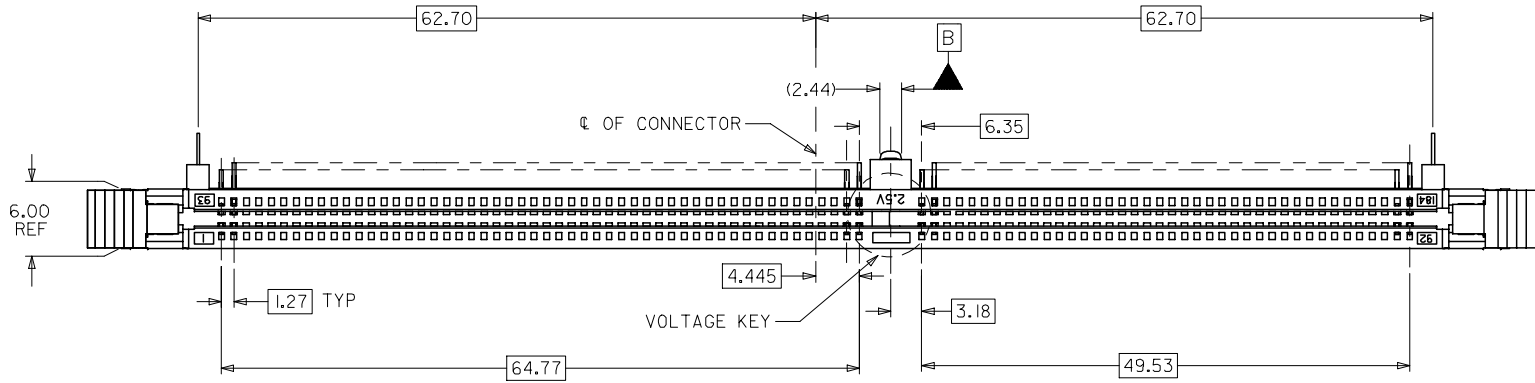
**Mates With**

JEDEC MO-206 modules

This document was generated on 04/09/2010

**PLEASE CHECK [WWW.MOLEX.COM](http://WWW.MOLEX.COM) FOR LATEST PART INFORMATION**

10 9 8 7 6 5 4 3 2 1



- NOTES:
- MATERIALS: HOUSING & BASEPLATE - LCP, GLASS FILLED, UL 94V-0, COLOR: BLACK  
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0, COLOR: BEIGE  
TERMINAL AND FORKLOCK - COPPER ALLOY
  - FINISHES: CONTACT AREA: SEE TABLE ON SHEET 4  
SOLDER TAILS: 2.54μm/100μ" MIN. TIN  
OVER 1.27mm/50μ" MIN. NICKEL
  - PRODUCT SPECIFICATIONS: PS-87623-002 FOR PERFORMANCE SPECIFICATIONS.
  - DATE CODE SHALL BE MARKED LEGIBLY AS SHOWN: XX XX  
YEAR — WEEK
  - PART NUMBER SHALL BE MARKED LEGIBLY AS SHOWN: 87623-0XXX  
REFER TO TABLE

OBS TIN/LEAD P/N	EC NO: S2006-0734	2006/02/27	QUALITY SYMBOLS
	DRWN:MLG	2006/02/28	
	CHKD:HO	2006/03/01	
	APPR:GJLEE		
REV	DESCRIPTION		

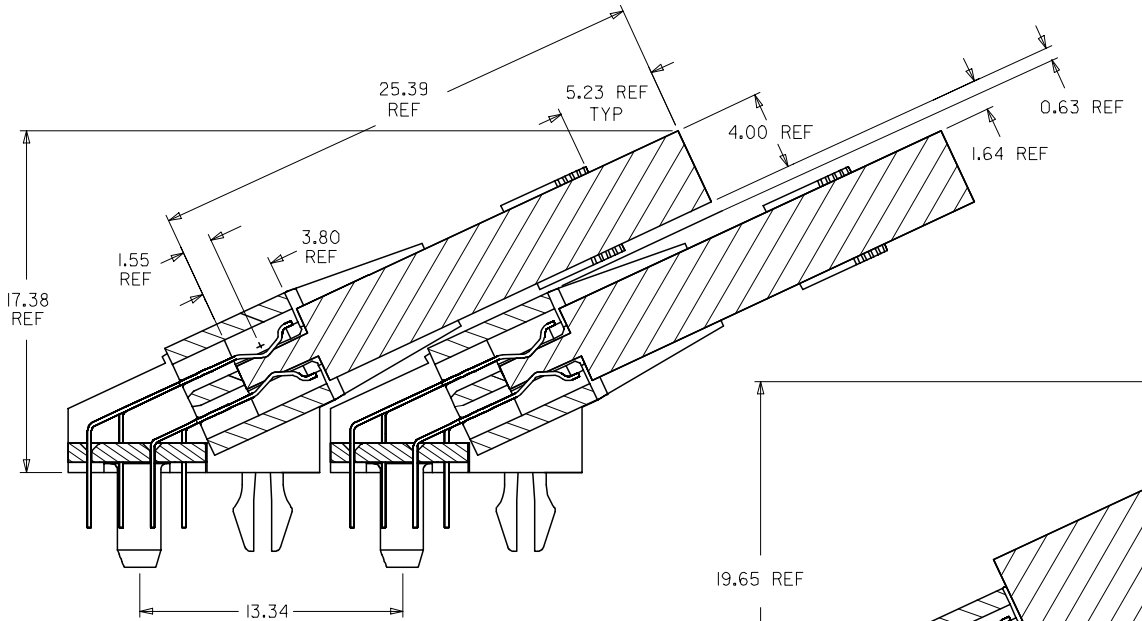
QUALITY SYMBOLS	▽=0	
	∇=0	
GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
	4 PLACES ± ---	± ---
	3 PLACES ± ---	± ---
	2 PLACES ± 0.25	± ---
	1 PLACE ± ---	± ---
	ANGULAR ± 5 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		NTS	METRIC	
DRAWN BY	DATE	TITLE		
LPL IM	2000/01/10	DDR DIMM, 1.27MM PITCH		
CHECKED BY	DATE	184 CKTS, 25 DEG.		
DSOH	2000/02/02			
APPROVED BY	DATE	MOLEX INCORPORATED		
SKTOH	2000/02/02			
MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
SEE TABLE	SD-87623-001	1 OF 4		
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

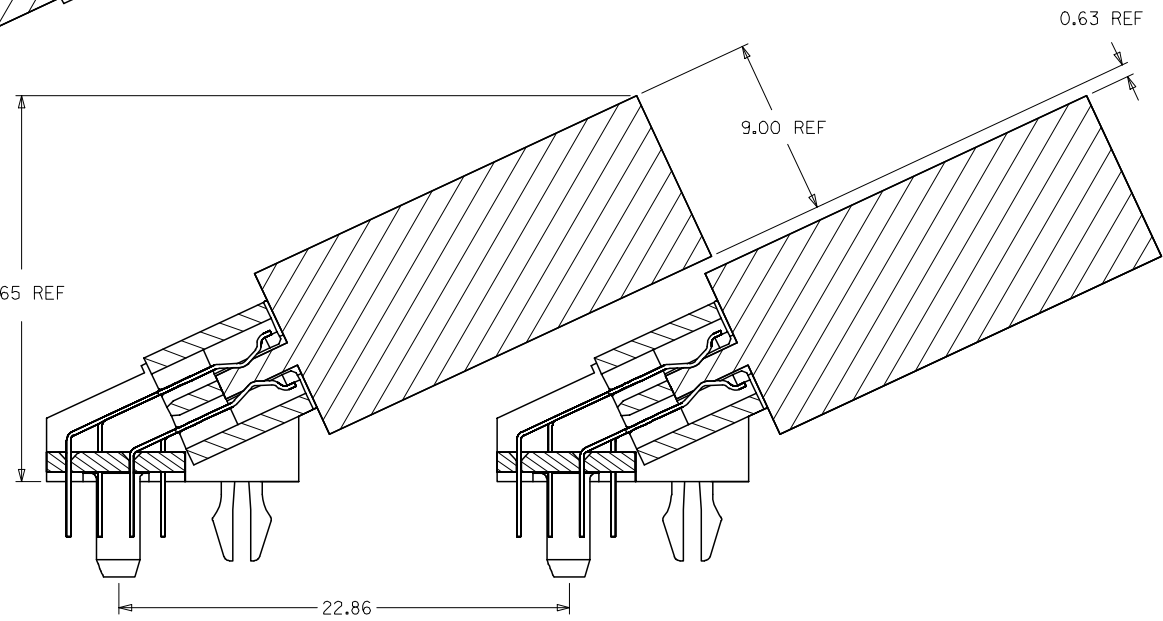
9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

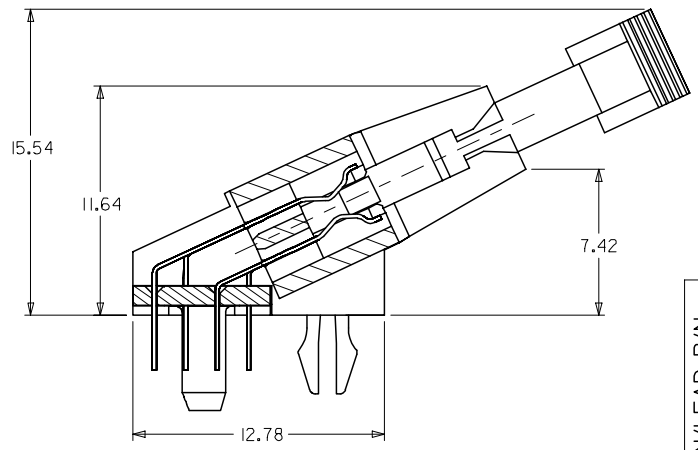
F  
E  
D  
C  
B  
A



MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 4.00 mm THICK  
MODULE (TYPICAL TSOP PACKAGING)



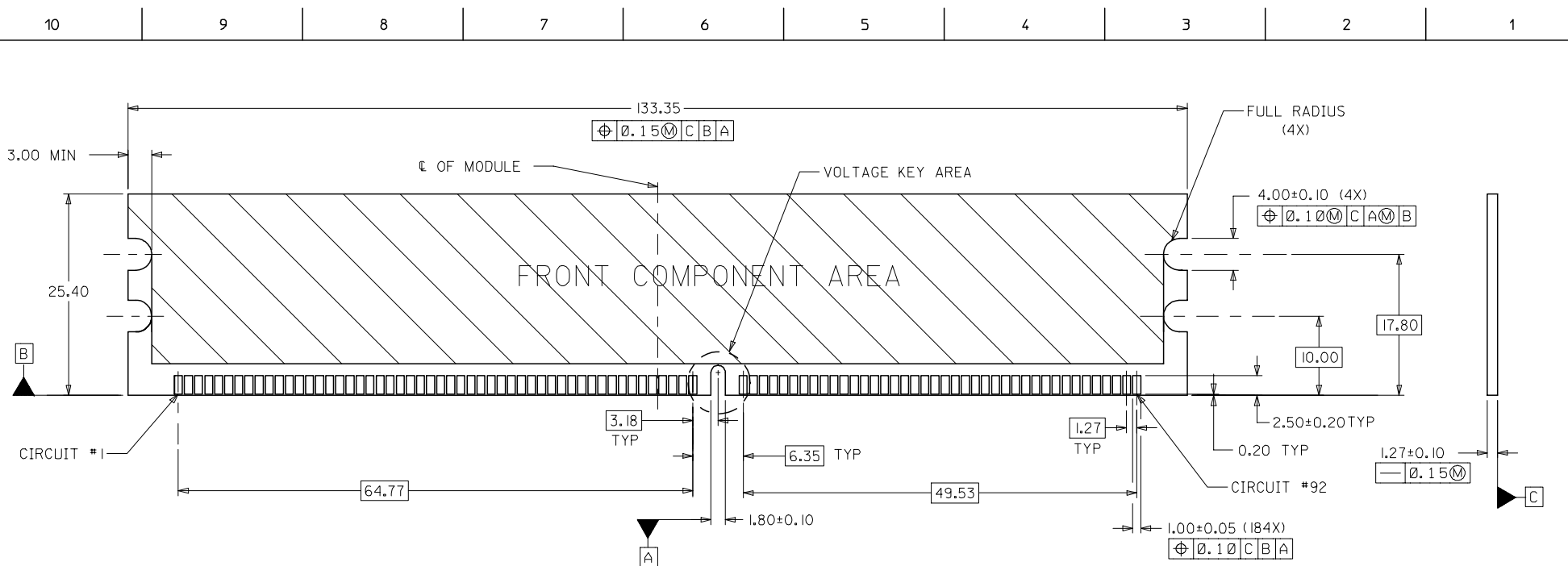
MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 9.00 mm THICK  
MODULE (TYPICAL SOJ PACKAGING)



SECTION A-A

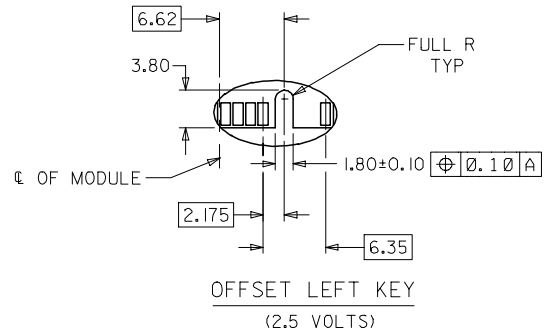
OBS TIN/LEAD P/N EC NO: S2006-0734 DRWN:MLONG CHKD:IHO APPR:GJLEE	2006/02/27	QUALITY SYMBOLS ▽=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	2006/02/28		4 PLACES ± ---	mm	INCH	DRAWN BY LPL IM	DATE 2000/01/10	TITLE DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.		
	2006/03/01		3 PLACES ± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY SKTOH	DATE 2000/02/02	MOLEX INCORPORATED		
			2 PLACES ± 0.25	SEE TABLE		MATERIAL NO.	DOCUMENT NO. SD-87623-001	SHEET NO. 2 OF 4		
		1 PLACE ± ---			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			ANGULAR ± 5 °							

9 8 7 6 5 4 3 2 1



RECOMMENDED MODULE LAYOUT  
 (PER JEDEC STANDARD MO-206, 184 CKT.)  
 UNLESS OTHERWISE SPECIFIED, GENERAL TOLERANCE FOR MODULE = ±0.13

VOLTAGE KEY AREA



OBS TIN/LEAD P/N	2006/02/27
EC NO: S2006-0734	2006/02/28
DRWN:MLONG	2006/03/01
CHKD:HO	
APPR:GGLLEE	
REV	DESCRIPTION

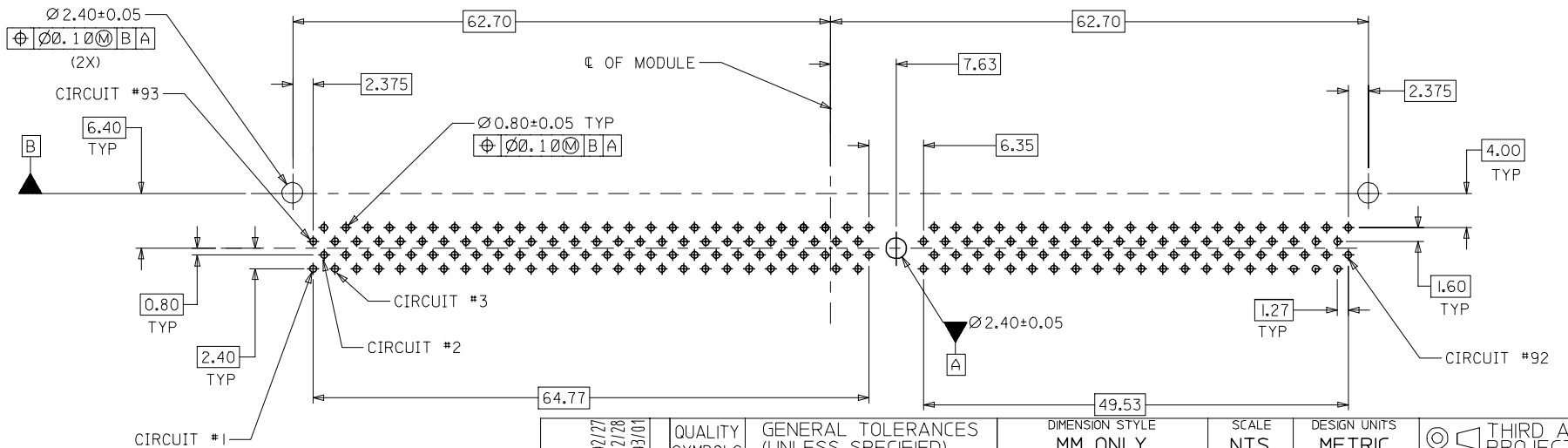
QUALITY SYMBOLS	▽=0
	∇=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
	4 PLACES ± ---	± ---
	3 PLACES ± ---	± ---
	2 PLACES ± 0.25	± ---
	1 PLACE ± ---	± ---
	ANGULAR ± 5 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		NTS	METRIC	
DRAWN BY	DATE	TITLE		
LPL IM	2000/01/10	DDR DIMM, 1.27MM PITCH		
CHECKED BY	DATE	184 CKTS, 25 DEG.		
DSOH	2000/02/02			
APPROVED BY	DATE			
SKTOH	2000/02/02			
MATERIAL NO.	DOCUMENT NO.			
SEE TABLE	SD-87623-001			
SIZE				
A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

MOLEX INCORPORATED		SHEET NO.
		3 OF 4

PART NUMBER	VOLTAGE KEY	CKT SIZE	TAIL LENGTH P±0.25	PEG LENGTH 0±0.25	FORK LENGTH R±0.25	RECOMMENDED PCB THICKNESS	FINISHES: CONTACT AREA
87623-2001	LEFT (2.5V)	184	2.79	3.18	3.18	1.57	SELECTIVE GOLD 0.38µM/15µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL
87623-2011			3.18	4.83	3.94		
87623-2012			3.18	3.18	3.18		
87623-2013			3.81	4.83	4.42	2.84	
87623-2101			2.79	3.18	3.18	1.57	
87623-2111			3.18	4.83	3.94		
87623-2113			3.81	4.83	4.42		
87623-2115			3.18	3.18	3.18	1.57	SELECTIVE GOLD 0.76µM/30µ" MIN. GOLD OVER 1.27µM/50µ" MIN. NICKEL



RECOMMENDED  
P.C. BOARD HOLE PATTERN  
(CONNECTOR SIDE)

OBS TIN/LEAD P/N	2006/02/27
EC NO: S2006-0734	2006/02/28
DRWN:HLONG	2006/02/28
CHKD:HO	2006/03/01
APPR:GJLEE	

QUALITY SYMBOLS	DESCRIPTION
▽=0	
▽=0	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± 0.25	± ---
1 PLACE ± ---	± ---
ANGULAR ± 5 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
LPL IM	2000/01/10
CHECKED BY	DATE
DSOH	2000/02/02
APPROVED BY	DATE
SKTOH	2000/02/02
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	
TITLE		
DDR DIMM, 1.27MM PITCH 184 CKTS, 25 DEG.		
MOLEX INCORPORATED		
DOCUMENT NO.	SHEET NO.	
SD-87623-001	4 OF 4	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		